

Technical Data Sheet

EverTherm CS series is a composite material which offers extremely high thermal conductivity, low density and good durability. Carbon fiber is an anisotropic and offering a very high level of thermal conductivity in the Z axis. This silica gel sheet is very soft and well compressed, it is used to fill the interface of two substrates, ensuring air from the interface is discharged, and heat conduction dramatically improved. Thermal conductivity @ 15.0W/M.K



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good flexibility and high compression ratio

Adhesive optional:

- -Al equals single-sided adhesive;
- -A2 equals double-sided adhesive

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- Communication & power devises & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVCSF15 15W Visual Color Black 1.0 ~ 20.0mm **Thickness** ASTM D374 *** Metal Bilicone rubbeł Filler Carbon 2.8g/cm3 ASTM D792 Density 15.0W/m-K Thermal Conductivity ASTM D5470 Hardness (Shore 00) 40~90 **ASTM D2240** 40/60±5 Normal Hardness (Shore 00) **ASTM D2240** 40% Elongation ASTM D412 Tensile Strength 30psi ASTM D412 0.11 *in2/W Thermal Resistance (1mm,@40psi) **ASTM D5470** Operating Temperature(°C) -50~ 160 **ASTM D1329**

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

PASS

EN14372

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Note: The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.